Examples, the adhesive compositions according to the invention surprisingly satisfy these requirements to a very high degree.

IN THE CLAIMS

On page 20, line 1, please replace the heading "CLAIMS" with the following heading:

-- We claim: --

Please cancel claims 1-14 without prejudice.

Please enter new claims 15-30 as follows.

15. A structural adhesive with good low temperature impact strength which comprises:

A) a copolymer having at least one glass transition temperature of -30°C or lower and epoxy-reactive groups or a reaction product of this copolymer with a polyepoxide;

B) a reaction product of a polyurethane prepolymer and a polyphenol or aminophenol; and

C) at least one epoxy resin.

16. The composition claimed in claim 15, wherein component A) comprises a butadiene-based copolymer.

17. The composition claimed in claim 16, wherein the copolymer of component A) comprises a carboxyl-containing copolymer based on at least one member selected from the group consisting of butadiene/acrylonitrile, butadiene/(meth)acrylate copolymer, butadiene/acrylonitrile/styrene copolymer and butadiene/(meth)-acrylate/styrene copolymer.

18. The composition claimed in claim 15, wherein the copolymer of component A) comprises a core/shell polymer of which the core polymer is a diene polymer or a (meth)acrylate polymer with a glass transition temperature of -30°C or lower and

which may optionally be crosslinked with 0.01 to 5% by weight of a diolefinic comonomer and of which the shell polymer has a glass transition temperature of 60°C or higher and contains residues of at least one monomer selected from the group consisting of alkyl (meth)acrylate, (meth)acrylonitrile, (methyl) styrene, olefinically unsaturated carboxylic acids, olefinically unsaturated carboxylic anhydrides and mixtures thereof.

19. The composition claimed in claim 15 wherein component A comprises an adduct of an epoxy resin and a butadiene based copolymer.

20. The composition claimed in claim 15 wherein component B) comprises a compound of the formula:

$$R^1\text{-}[X\text{-}(C{=}O)\text{-}NH\text{-}R^2\text{-}NH\text{-}(C{=}O)\text{-}Y\text{-}R^3\text{-}(Z)_m]_n \qquad (I)$$

in which

m = 1 or 2,

n = 2 or 3,

R^1 is a residue of a polyalkylene glycol after removal of the functional groups (hydroxyl or amino groups),

R^2 = $C_{6\text{-}14}$ alkyl, aryl, aralkyl (residue of a diisocyanate after removal of the isocyanate groups),

X,Y = -O-, -S- or -NR^4-, where R^4 = H or $C_{1\text{-}4}$ alkyl or phenyl,

R^3 is a carbocyclic-aromatic or araliphatic m+1-functional residue with groups Z directly attached to the aromatic ring and Z = -OH or -NHR^4 (residue of a polyphenol or aminophenol after removal of the functional groups).

21. The composition claimed in claim 15, wherein component B) is dissolved in a liquid polyepoxide.

22. The composition claimed in claim 15, wherein component B) is reacted with a stoichiometric excess of a polyepoxide.

23. The composition claimed in claim 15 further comprising

D) a latent hardener selected from the group consisting of dicyanodiamide, guanamines, guanidines, aminoguanidines, solid aromatic diamines and mixtures thereof and optionally a hardening accelerator; and

E) optionally plasticizers, reactive diluents, rheology aids, fillers, wetting agents, antiagers and stabilizers.

24. A cured composition of claim 15 having an impact peel energy of at least 5 J at -20°C (to ISO 11343).

25. The production of composite materials, potting compounds in the electrical and electronics industries and die-attach adhesive for the production of circuit boards in the electronics industry wherein the adhesive comprises the composition of claim 24.

26. The composition of claim 15 further comprising:

D) a latent hardener selected from the group consisting of dicyanodiamide, guanamines, guanidines, aminoguanidines, solid aromatic diamines and mixtures thereof and optionally a hardening accelerator;

E) optionally plasticizers, reactive diluents, rheology aids, fillers, wetting agents, antiagers and stabilizers;

F) a polyester polyol with a molecular weight of 400 to 5,000; and

G) optionally a thermoplastic polymer powder.

27. A process for hardening a composition of claim 26 which comprises heating the composition to a temperature of 80°C to 210°C.

28. A process for bonding metallic and/or composite materials comprising:

- applying the adhesive composition claimed in claim 26 to at least one of the substrate surfaces to be joined, optionally after cleaning and/or surface treatment
- fitting the parts to be joined together
- optionally pregelling the adhesive composition and
- curing the bond by heating the parts to a temperature of from 80°C to 210°C.

29. The process of claim 28 wherein the bond is cured at a temperature of from